

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3730029

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIEN-WEI WANG	01/29/2010
MING-FENG SHIEH	01/29/2010
CHING-YU CHANG	01/29/2010
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14727317
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2146515000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP
Address Line 1:	2323 VICTORY AVENUE, SUITE 700
Address Line 2:	IP SECTION
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.1368US02
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	02/08/2016
Total Attachments: 2	
source=assignment#page1.tif	
source=assignment#page2.tif	

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Chien-Wei Wang | of | No. 2, Alley 74, Lane 296, Minsheng Road
Wufong Township, Taichung County 413, Taiwan, R.O.C. |
| (2) | Ming-Feng Shieh | of | No. 68, Lane 186, Shenglong Street
Yongkang City, Tainan County 710, Taiwan, R.O.C. |
| (3) | Ching-Yu Chang | of | No. 17, Hsinchen Road
Yuansun Village, Yilang County 264, Taiwan, R.O.C. |

have invented certain improvements in

METHOD AND APPARATUS OF PATTERNING A SEMICONDUCTOR DEVICE

for which we filed an application for Letters Patent of the United States of America on December 30, 2009, as U.S. Serial No. 12/649,462; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chien-Wei Wang

Residence Address: No. 2, Alley 74, Lane 296, Minsheng Road
Wufong Township, Taichung County 413, Taiwan, R.O.C.

Dated: 2010.1.29

王連惟 Chien Wei Wang
Inventor Signature

Inventor Name: Ming-Feng Shieh

Residence Address: No. 68, Lane 186, Shenglong Street
Yongkang City, Tainan County 710, Taiwan, R.O.C.

Dated: 2010.1.29

謝明峰 Ming Feng Shieh
Inventor Signature

Inventor Name: Ching-Yu Chang

Residence Address: No. 17, Hsinchen Road
Yuansun Village, Yilang County 264, Taiwan, R.O.C.

Dated: 2010.1.29

Ching-Yu Chang
Inventor Signature